

**Amendments to the Claims:**

Applicant has amended claims 1, 8 and 9, and added a new claim 21. Claims 13-20 are canceled.

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

**Claim 1 (currently amended):** A package of a semiconductor device with a flexible wiring substrate, comprising:

a semiconductor substrate with having said semiconductor device and at least one pad on a surface thereof;

a plate located above said surface of said semiconductor substrate, said semiconductor device is covered by said plate, and said at least one pad is uncovered by said plate;

a bump bonded to said pad;

an adhesive layer on said bump; and

a said flexible wiring substrate having at least one contact section being electrically connected with said bump by said adhesive layer.

**Claim 2 (original):** The package of claim 1, wherein said bump is stud bump.

**Claim 3 (original):** The package of claim 2, wherein said bump is gold stud bump.

**Claim 4 (original):** The package of claim 1, wherein said adhesive layer includes non-conductive paste.

**Claim 5 (original):** The package of claim 2, wherein said adhesive layer includes non-conductive paste.

**Claim 6 (original):** The package of claim 1, wherein said adhesive layer includes anistropic conductive paste.

**Claim 7 (original):** The package of claim 2, wherein said adhesive layer includes anistropic conductive paste.

**Claim 8 (currently amended):** The package of claim 1, wherein said semiconductor ~~substrate device comprises one or more having~~ image sensors ~~on the surface thereof having said pad.~~

**Claim 9 (currently amended):** The package of claim 8, wherein ~~said plate is~~ a transparent plate ~~covered on the surface of said semiconductor substrate having said image sensors.~~

**Claim 10 (original):** The package of claim 9, wherein said bump is stud bump.

**Claim 11 (original):** The package of claim 10, wherein said adhesive layer includes anistropic conductive paste.

**Claim 12 (original):** The package of claim 10, wherein said adhesive layer includes non-conductive paste.

**Claims 13-20 (Canceled)**

**Claim 21 (new):** The package of claim 1, wherein said plate is held by an adhesive material and located above said semiconductor substrate.